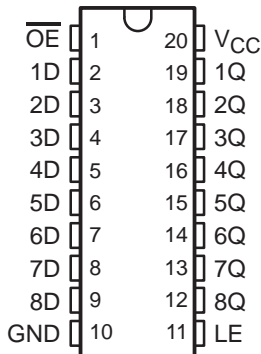


SN54ABT573, SN74ABT573A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

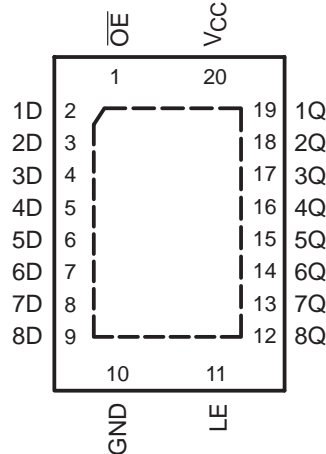
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- Typical V_{OLP} (Output Ground Bounce) <1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

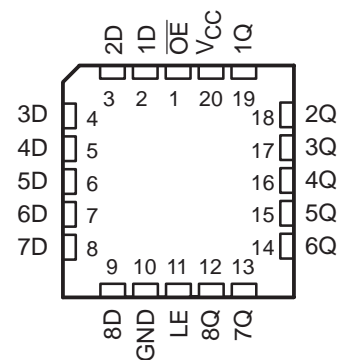
SN54ABT573 . . . J OR W PACKAGE
SN74ABT573A . . . DB, DW, N, NS,
OR PW PACKAGE
(TOP VIEW)



SN74ABT573A . . . RGY PACKAGE
(TOP VIEW)



SN54ABT573 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74ABT573AN	SN74ABT573AN
	QFN – RGY	Tape and reel	SN74ABT573ARGYR	AB573A
	SOIC – DW	Tube	SN74ABT573ADW	ABT573A
		Tape and reel	SN74ABT573ADWR	
	SOP – NS	Tape and reel	SN74ABT573ANSR	ABT573A
	SSOP – DB	Tape and reel	SN74ABT573ADBR	AB573A
	TSSOP – PW	Tube	SN74ABT573APW	AB573A
		Tape and reel	SN74ABT573APWR	
	VFBGA – GQN	Tape and reel	SN74ABT573AGQNR	AB573A
	VFBGA – ZQN (Pb-free)	Tape and reel	SN74ABT573AZQNR	
-55°C to 125°C	CDIP – J	Tube	SNJ54ABT573J	SNJ54ABT573J
	CFP – W	Tube	SNJ54ABT573W	SNJ54ABT573W
	LCCC – FK	Tube	SNJ54ABT573FK	SNJ54ABT573FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54ABT573, SN74ABT573A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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description/ordering information (continued)

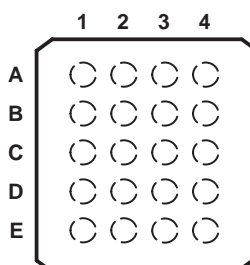
A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

\overline{OE} does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

SN74ABT573A . . . GQN OR ZQN PACKAGE (TOP VIEW)



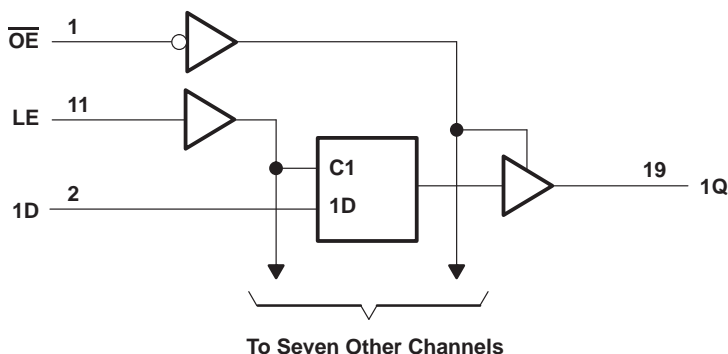
terminal assignments

	1	2	3	4
A	1D	\overline{OE}	V_{CC}	1Q
B	3D	3Q	2D	2Q
C	5D	4D	5Q	4Q
D	7D	7Q	6D	6Q
E	GND	8D	LE	8Q

FUNCTION TABLE (each latch)

INPUTS			OUTPUT
\overline{OE}	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, FK, J, N, NS, PW, RGY, and W packages.

SN54ABT573, SN74ABT573A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	-0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT573	96 mA
SN74ABT573A	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	-18 mA
Output clamp current, I_{OK} ($V_O < 0$)	-50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	70°C/W
(see Note 2): DW package	58°C/W
(see Note 2): GQN/ZQN package	78°C/W
(see Note 2): N package	69°C/W
(see Note 2): NS package	60°C/W
(see Note 2): PW package	83°C/W
(see Note 3): RGY package	37°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 3. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 4)

	SN54ABT573		SN74ABT573A		UNIT
	MIN	MAX	MIN	MAX	
V_{CC} Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH} High-level input voltage	2		2		V
V_{IL} Low-level input voltage		0.8		0.8	V
V_I Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH} High-level output current		-24		-32	mA
I_{OL} Low-level output current		48		64	mA
$\Delta t/\Delta v$ Input transition rise or fall rate	Outputs enabled		5	5	ns/V
T_A Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN54ABT573, SN74ABT573A

OCTAL TRANSPARENT D-TYPE LATCHES

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T _A = 25°C			SN54ABT573		SN74ABT573A		UNIT	
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX		
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.2		-1.2		-1.2	V	
V _{OH}	V _{CC} = 4.5 V, I _{OH} = -3 mA			2.5		2.5		2.5	V	
	V _{CC} = 5 V, I _{OH} = -3 mA			3		3		3		
	V _{CC} = 4.5 V	I _{OH} = -24 mA			2		2			
I _{OH} = -32 mA				2*				2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA				0.55		0.55	V	
		I _{OL} = 64 mA				0.55*		0.55		
V _{hys}				100					mV	
I _I	V _{CC} = 5.5 V, V _I = V _{CC} or GND			±1		±1		±1	μA	
I _{OZH}	V _{CC} = 5.5 V, V _O = 2.7 V			10‡		10‡		10‡	μA	
I _{OZL}	V _{CC} = 5.5 V, V _O = 0.5 V			-10‡		-10‡		-10‡	μA	
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V			±100				±100	μA	
I _{CEX}	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high				50		50	μA	
I _{O§}	V _{CC} = 5.5 V, V _O = 2.5 V			-50	-100	-180		-50	-180	mA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		1	250			250	250	μA
		Outputs low		24	30			30	30	mA
		Outputs disabled		0.5	250			250	250	μA
ΔI _{CC¶}	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND					1.5		1.5	1.5	mA
C _i	V _I = 2.5 V or 0.5 V					3.5				pF
C _o	V _O = 2.5 V or 0.5 V					6.5				pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ This data sheet limit may vary among suppliers.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54ABT573				UNIT	
		V _{CC} = 5 V, T _A = 25°C		MIN	MAX		
		MIN	MAX				
t _w	Pulse duration, LE high			3.3		3.3	ns
t _{su}	Setup time, data before LE↓	High		1.9		2.5	ns
		Low		1.5		2.5	
t _h	Hold time, data after LE↓			1		2.5	ns



SN54ABT573, SN74ABT573A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN74ABT573A				UNIT	
		V _{CC} = 5 V, T _A = 25°C			MIN		MAX
		MIN	MAX				
t _w	Pulse duration, LE high		3.3		3.3	ns	
t _{su}	Setup time, data before LE↓	High	1.9		1.9	ns	
		Low	1.5		1.5		
t _h	Hold time, data after LE↓		1.8†		1.8†	ns	

† This data-sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT573					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t _{PLH}	D	Q	1.9	3.2	5.4	1.4	6.4	ns
t _{PHL}			2.2	4.2	5.7	1.6	6.7	
t _{PLH}	LE	Q	2.2	4	6.1	2	7.1	ns
t _{PHL}			3.2	5.2	6.7	2.8	7.5	
t _{PZH}	$\overline{\text{OE}}$	Q	1.2	3.2	4.7	0.8	6.2	ns
t _{PZL}			2.7	4.7	6.2	2	7.2	
t _{PHZ}	$\overline{\text{OE}}$	Q	2.5	4.9	6.4	2.2	7.7	ns
t _{PLZ}			2	4.2	6	1.4	7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT573A					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t _{PLH}	D	Q	1.9	3.2	5.4	1.9	5.9	ns
t _{PHL}			2.2	4.2	5.7	2.2	6.2	
t _{PLH}	LE	Q	2.2	4	6.1	2.2	6.6	ns
t _{PHL}			3.2	5.2	6.7	3.2	7.2	
t _{PZH}	$\overline{\text{OE}}$	Q	1.2	3.2	4.7	1.2	5.2	ns
t _{PZL}			2.5†	4.7	6.2	2.5†	6.7	
t _{PHZ}	$\overline{\text{OE}}$	Q	2.5	4.9	6.4	2.5	7.1†	ns
t _{PLZ}			2	4.2	6	2	6.5	

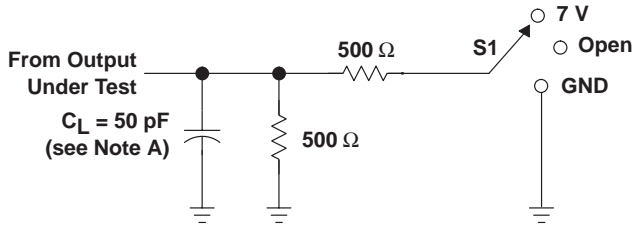
† This data-sheet limit may vary among suppliers.



SN54ABT573, SN74ABT573A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

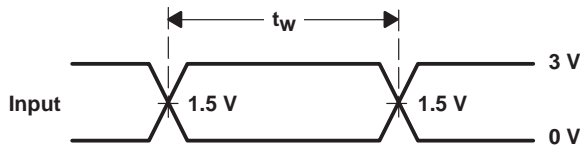
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PARAMETER MEASUREMENT INFORMATION

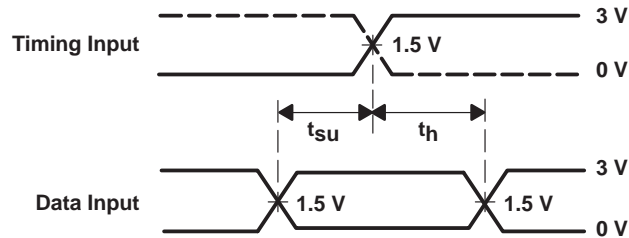


LOAD CIRCUIT

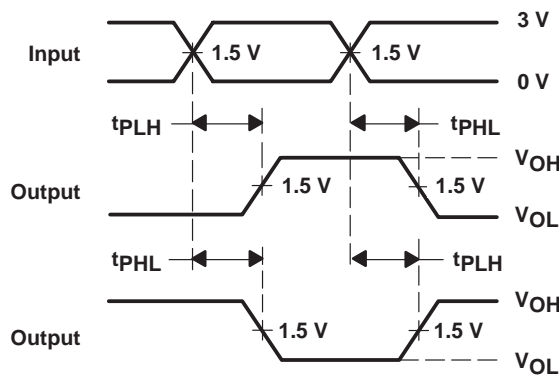
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



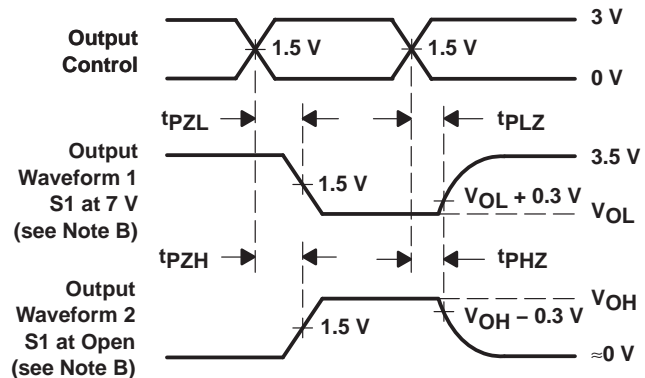
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

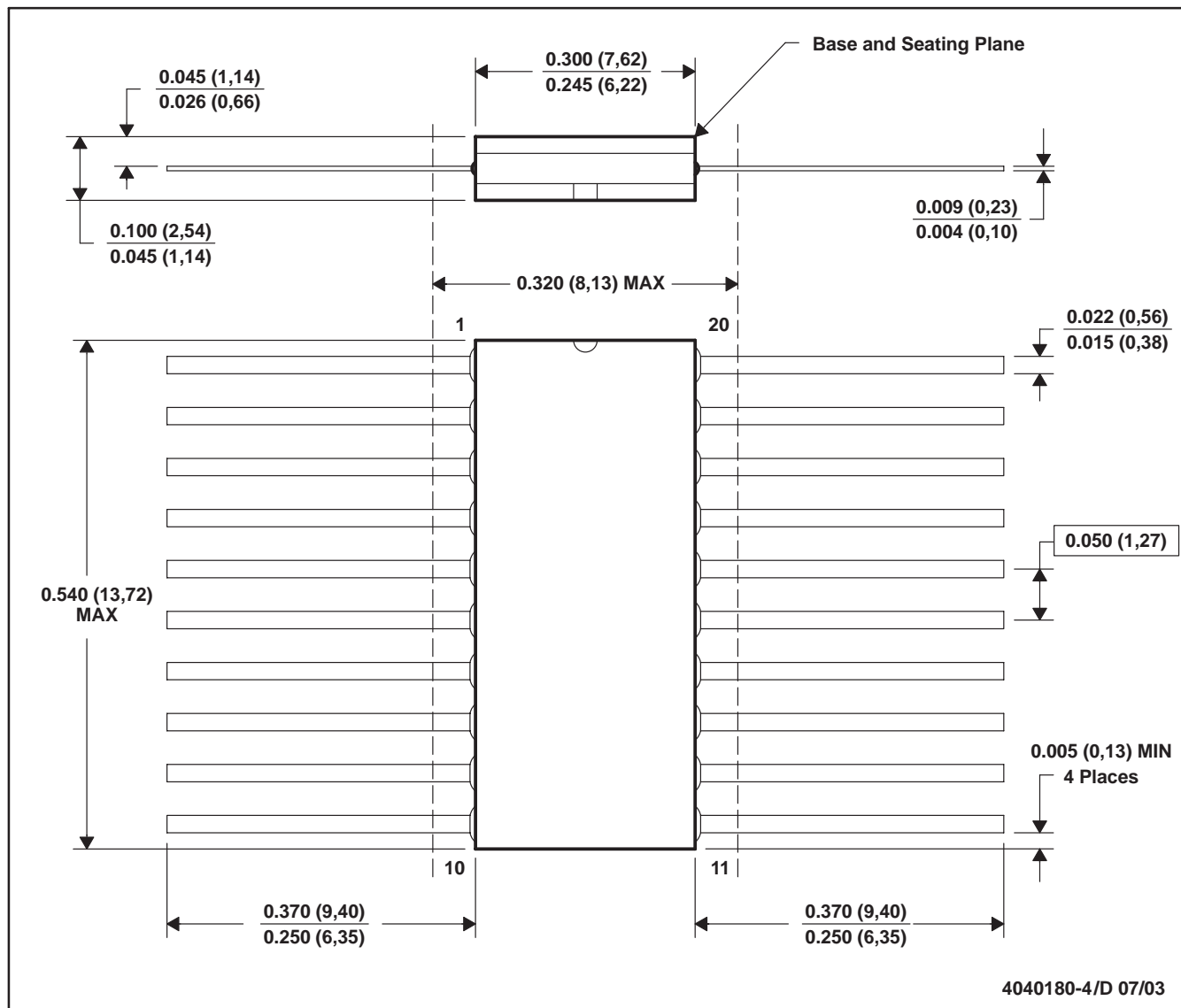


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

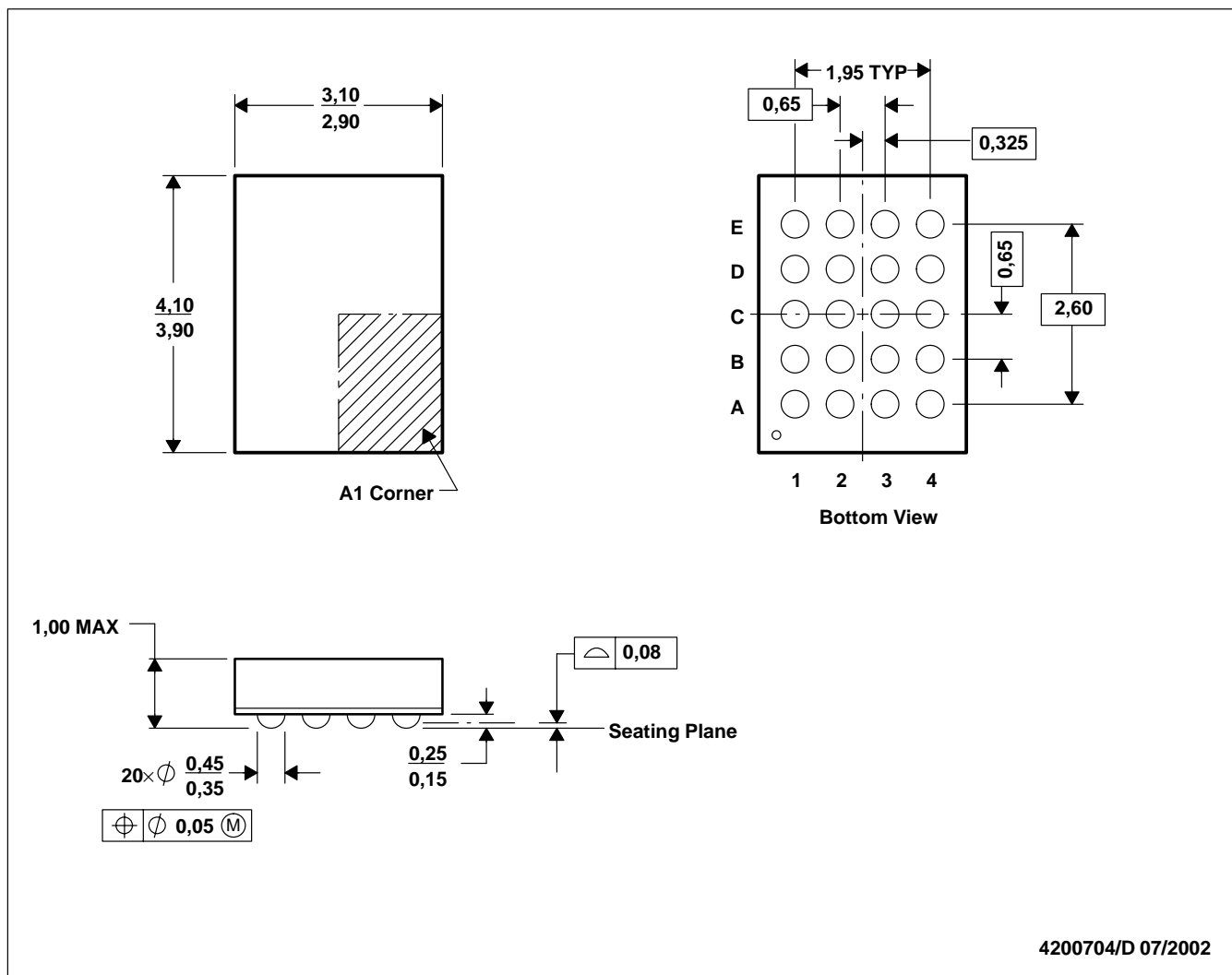
28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



4200704/D 07/2002

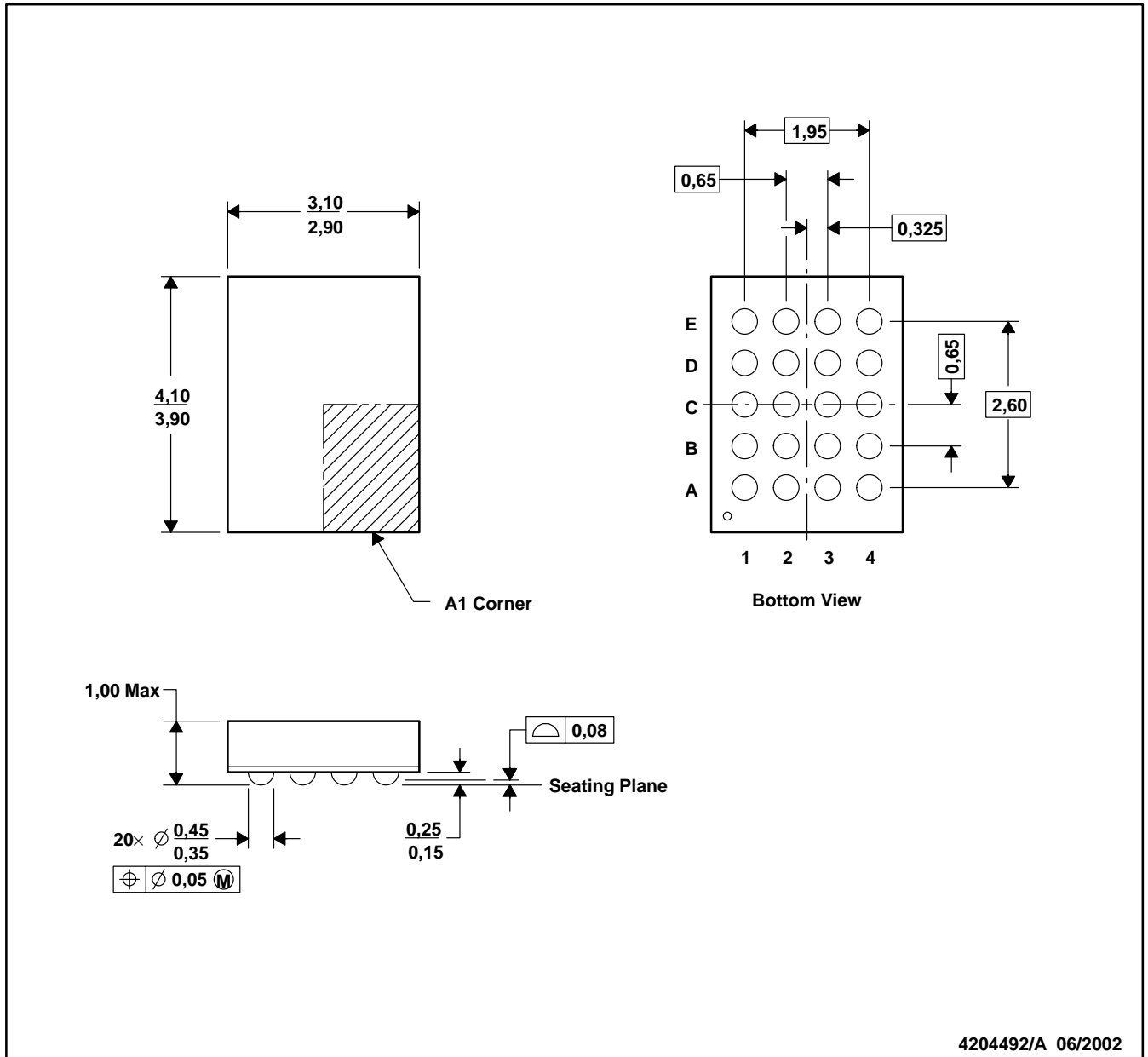
- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - MicroStar Junior™ configuration
 - Falls within JEDEC MO-225 variation BC.
 - This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

MicroStar Junior is a trademark of Texas Instruments.



ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



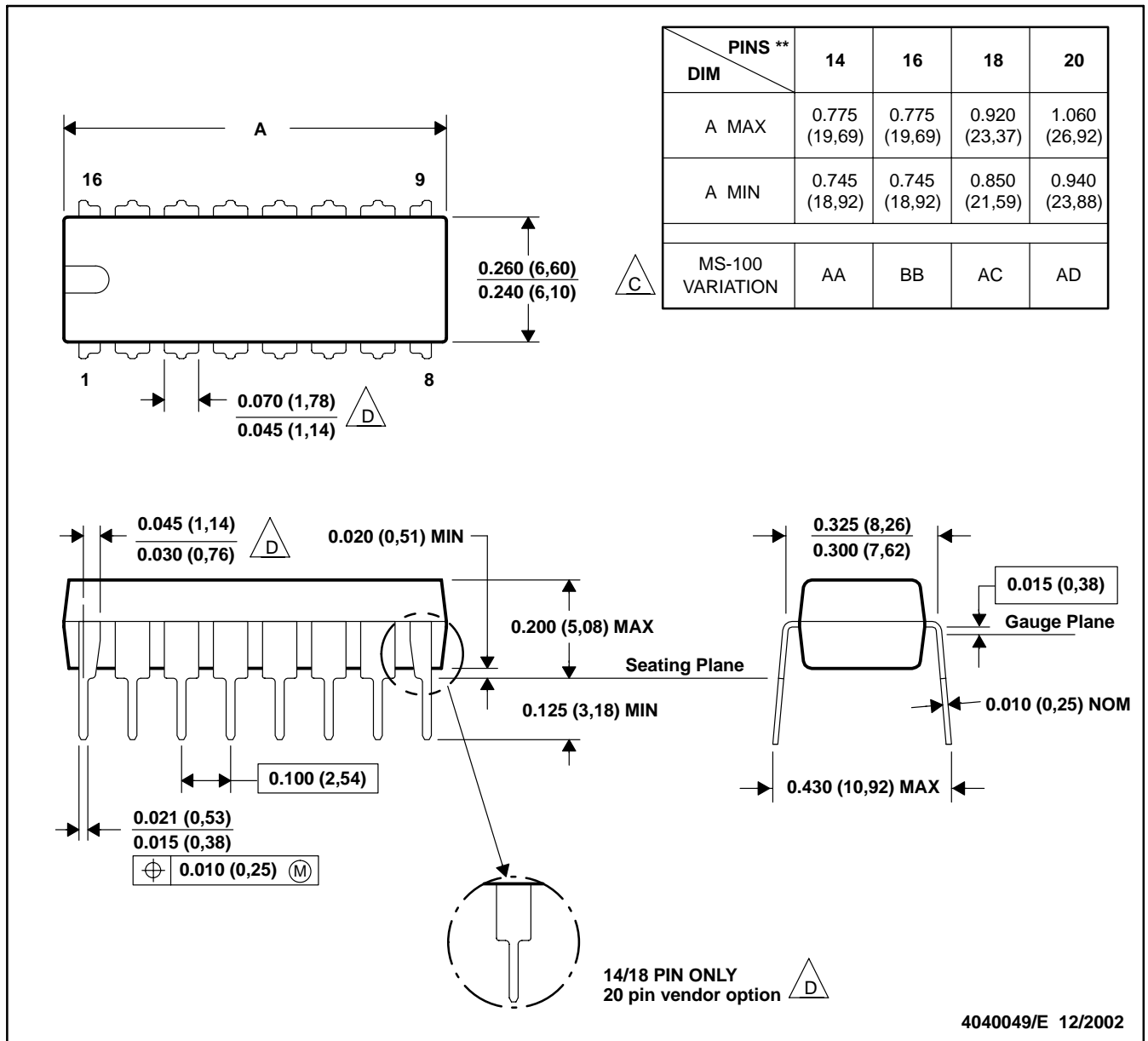
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. MicroStar Junior™ configuration.
 - D. Fall within JEDEC MO-225 variation BC.
 - E. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

MicroStar Junior is a trademark of Texas Instruments.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

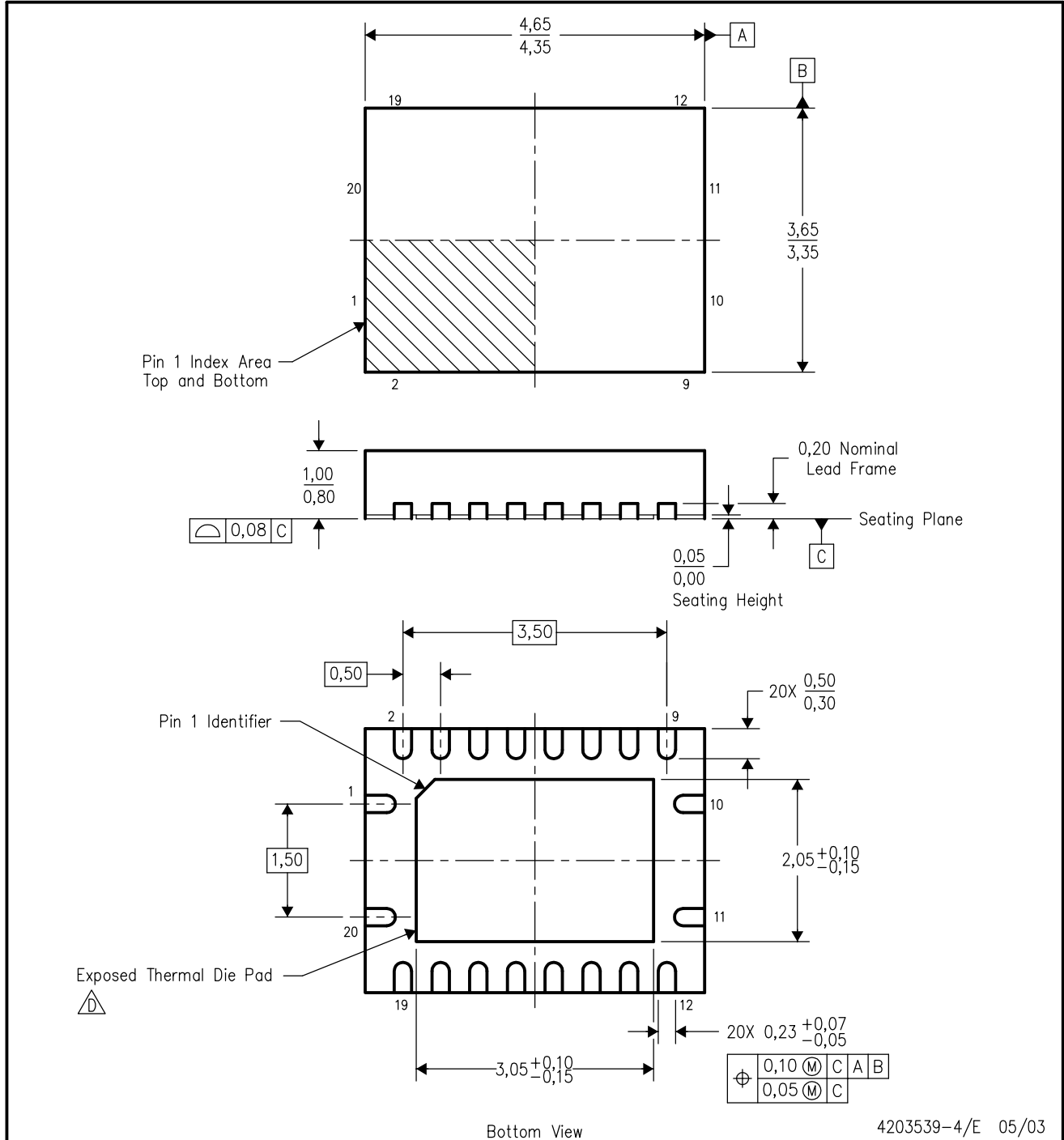
16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

RGY (R-PQFP-N20)

PLASTIC QUAD FLATPACK

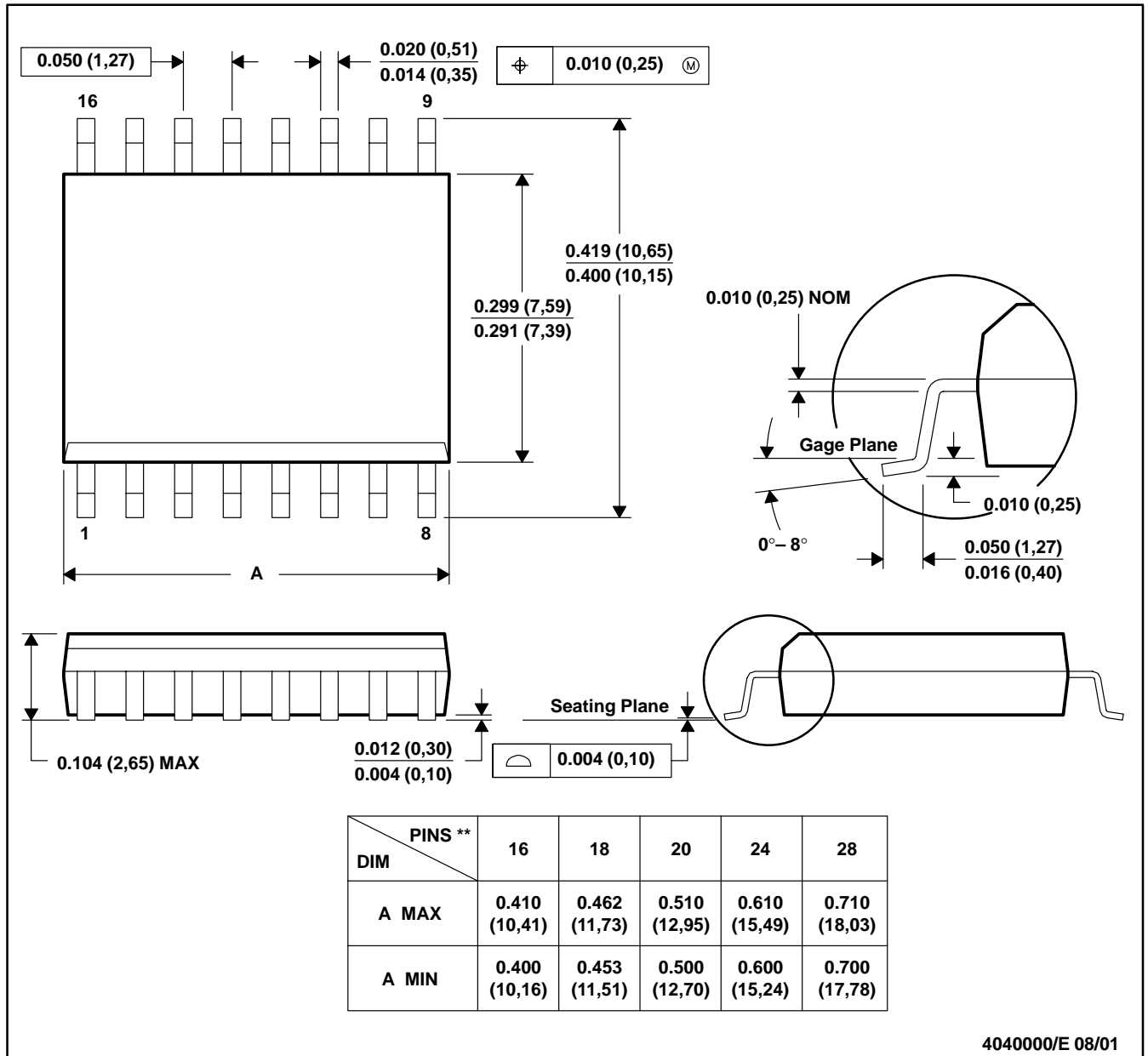


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BC.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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